

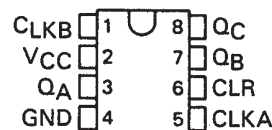
# SN54LS56, SN54LS57, SN74LS56, SN74LS57 FREQUENCY DIVIDERS

SDLS182 – DECEMBER 1983 – REVISED MARCH 1988

- 'LS56 Performs 50 to 1 Frequency Division (5 to 1, 5 to 1, and 10 to 1)
- 'LS57 Performs 60 to 1 Frequency Division (6 to 1, 5 to 1, and 10 to 1)
- Available in P or JG package (two P or JG Packages Fit in a Single 16-pin Socket)
- Maximum Clock Frequency 25 MHz Typical

SN54LS56, SN54LS57 . . . JG PACKAGE  
SN74LS56, SN74LS57 . . . JG OR P PACKAGE

(TOP VIEW)



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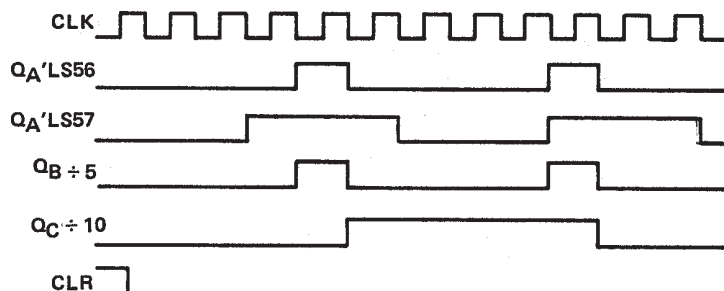
## description

These frequency dividers are particularly useful in generating one second or one hour timing pulses from 50 Hz (European standard frequency) or 60 Hz (United States standard frequency). 50 to 1 frequency division is accomplished in the 'LS56 by connecting output  $Q_A$  to input CLKB. 60 to 1 frequency division in the 'LS57 is accomplished in the same way. More universal capabilities are evidenced by the 25 MHz typical  $f_{max}$  and the almost limitless frequency division possibilities when used in cascade. Two 'LS56 packages may be interconnected to give frequency division of 2500 to 1, 625 to 1, 100 to 1, etc. Two 'LS57 packages can be connected to generate frequency divisions of 3600 to 1, 1800 to 1, 900 to 1 etc.

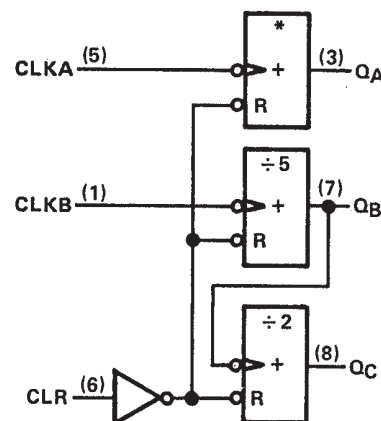
The 'LS56 and 'LS57 frequency dividers consist of three separate counters, A, B, and C on a single monolithic substrate. The A counter divides by 5 to 1 in the 'LS56 and by 6 to 1 in the 'LS57. The B counter divides by 5 to 1 in both devices and is internally tied to the C counter which divides by 2 to 1. The resulting C counter output is 10 to 1. Both the 'LS56 and 'LS57 feature a clear pin which is common to all three counters, A, B, and C. When the clear pin is low, the counters are enabled. When the clear is high, the counters are disabled and their outputs are set to a low-level.

All three counters, A, B, and C trigger on the high-to-low transition of the clock input. All output waveforms are symmetrical except for the 5 to 1 outputs (A and B of the 'LS56 and B of the 'LS57). See the output waveform drawings below.

## input and output waveforms

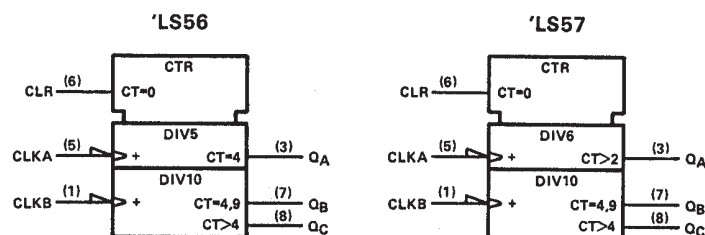


## logic diagram (positive logic)



\* 'LS56 ÷ 5  
'LS57 ÷ 6

## logic symbols†



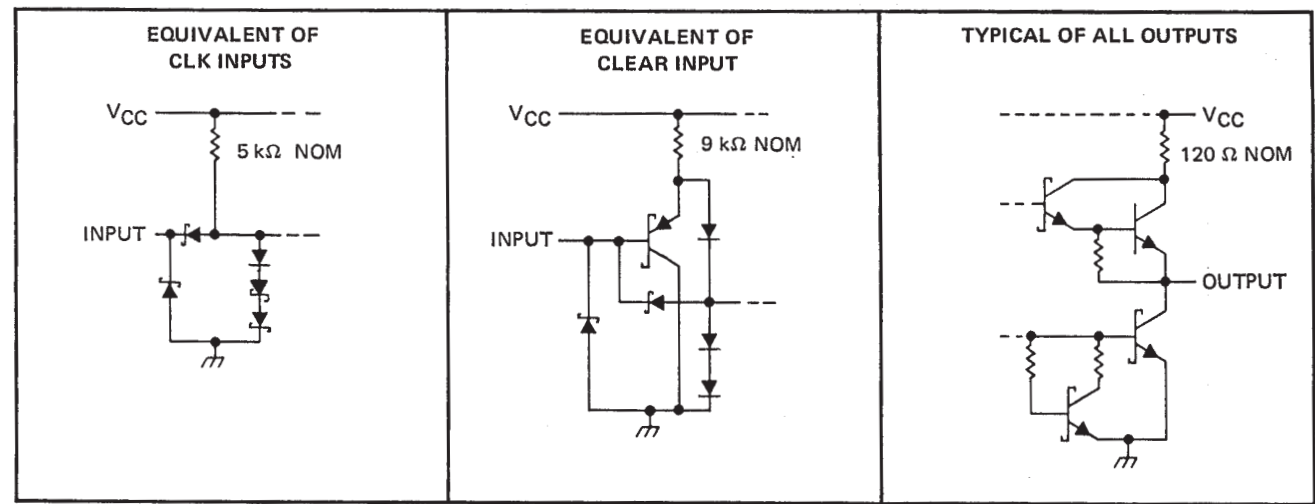
†These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

# SN54LS56, SN54LS57, SN74LS56, SN74LS57

## FREQUENCY DIVIDERS

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### schematics of inputs and outputs



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, $V_{CC}$ (see Note 1)	7 V
Input voltage: CLR	7 V
CLKA, CLKB	5.5 V
Operating free-air temperature range: SN54LS'	-55°C to 125°C
SN74LS'	-0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

### recommended operating conditions

		SN54LS'			SN74LS'			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
$V_{IH}$	High-level input voltage	2			2			V
$V_{IL}$	Low-level input voltage			0.7			0.8	V
$I_{OH}$	High-level output current			-1			-1	mA
$I_{OL}$	Low-level output current			8			16	mA
$f_{clock}$	Clock frequency	0		15	0		15	MHz
$t_r, t_f$	Rise and fall time of clock			50			50	ns
$t_w$	Pulse width of clock or clear	30			30			ns
$t_{su}$	Clear inactive state set-up time	25			25			ns
$T_A$	Operating free-air temperature	-55		125	0		70	°C

# SN54LS56, SN54LS57, SN74LS56, SN74LS57 FREQUENCY DIVIDERS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	SN54LS'			SN74LS'			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
$V_{IK}$		$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$			-1.5			-1.5	V
$V_{OH}$		$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = \text{MAX}, I_{OH} = -1 \text{ mA}$	2.5	3.4		2.7	3.4		V
$V_{OL}$		$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = \text{MAX}, I_{OL} = 8 \text{ mA}$	0.25	0.4		0.25	0.4		V
		$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = \text{MAX}, I_{OL} = 16 \text{ mA}$				0.35	0.5		
$I_I$	CLKA, CLKB	$V_{CC} = \text{MAX}$			$V_I = 5.5 \text{ V}$			0.2	mA
	CLR				$V_I = 7 \text{ V}$			0.1	
$I_{IH}$	CLKA, CLKB	$V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$			80			80	$\mu\text{A}$
	CLR				20			20	
$I_{IL}$	CLKA, CLKB	$V_{CC} = \text{MAX}, \text{CLR} = 0 \text{ V}, V_I = 0.4 \text{ V}$			-3.2			-3.2	mA
	CLR				-0.2			-0.2	
$I_{OS}\S$		$V_{CC} = \text{MAX}, \text{CLR} = 0 \text{ V}, V_O = 0 \text{ V}$	-20		-100	-20		-100	mA
$I_{CC}$		$V_{CC} = \text{MAX}, \text{See Note 2}$		17	30		17	30	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at  $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$ .

§ Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

NOTE 2:  $I_{CC}$  is measured by applying 4.5 V to the CLR pin with all other inputs grounded and the outputs open.

switching characteristics,  $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$  (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS56			'LS57			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
f <sub>max</sub>	CLKA	Q <sub>A</sub>	R <sub>L</sub> = 1 kΩ, C <sub>L</sub> = 30 pF	15	25		15	25		MHz
f <sub>max</sub>	CLKB	Q <sub>B</sub> , Q <sub>C</sub>		15	25		15	25		MHz
t <sub>PLH</sub>	CLKB	Q <sub>B</sub>		8	15		8	15		ns
t <sub>PHL</sub>				14	25		14	25		ns
t <sub>PLH</sub>	CLKB	Q <sub>C</sub>		18	30		18	30		ns
t <sub>PHL</sub>				24	35		24	35		ns
t <sub>PLH</sub>	CLKA	Q <sub>A</sub>		12	20		14	25		ns
t <sub>PHL</sub>				14	25		18	30		ns
t <sub>PHL</sub>	CLR	Q <sub>A</sub>		17	30		17	30		ns
t <sub>PHL</sub>	CLR	Q <sub>B</sub>		17	30		17	30		ns
t <sub>PHL</sub>	CLR	Q <sub>C</sub>		17	30		17	30		ns

†Times measured from CLKB to output  $Q_C$  are taken with output  $Q_B$  unloaded.

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LS56P	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI
SN74LS57P	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI
SN74LS57P	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

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**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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